

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ± 24 mA at 2.5-V V_{CC}

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

DESCRIPTION/ORDERING INFORMATION

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC) Circuitry Technology and Applications*, literature number SCEA009.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – DGG	Tape and reel	SN74AVC16374DGGR	AVC16374
	TVSOP – DGV	Tape and reel	SN74AVC16374DGVR	CVA374
	VFBGA – GQL	Tape and reel	SN74AVC16374GQLR	CVA374

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

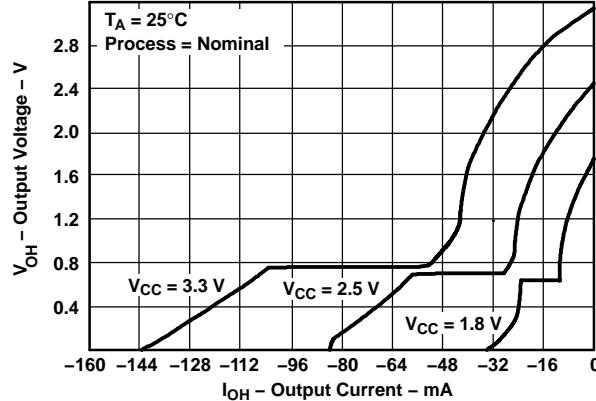
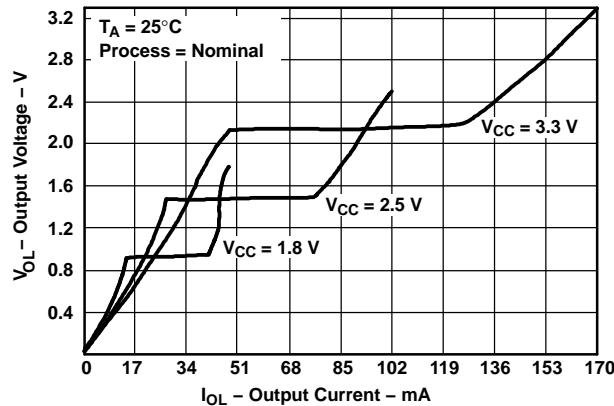


Figure 1. Output Voltage vs Output Current



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This 16-bit edge-triggered D-type flip-flop is operational at 1.2-V to 3.6-V V_{CC} , but is designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVC16374 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels at the data (D) inputs. \overline{OE} can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

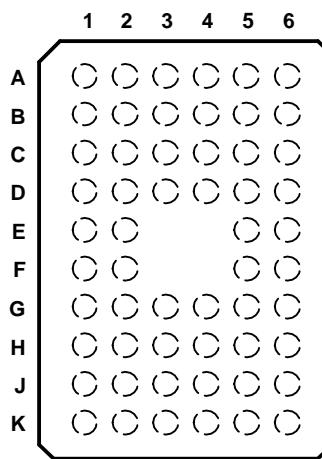
\overline{OE} does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16374 is characterized for operation from -40°C to 85°C .

**GQL PACKAGE
(TOP VIEW)**

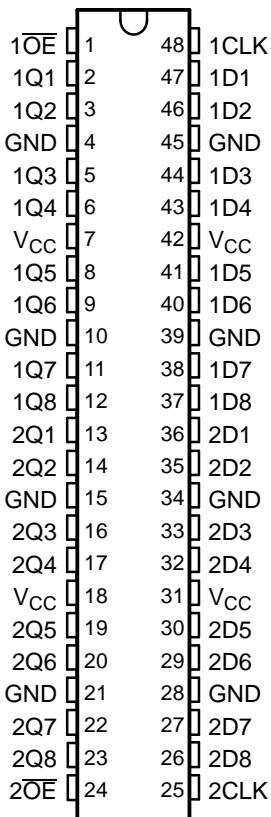


TERMINAL ASSIGNMENTS⁽¹⁾

	1	2	3	4	5	6
A	$1\overline{OE}$	NC	NC	NC	NC	1CLK
B	1Q2	1Q1	GND	GND	1D1	1D2
C	1Q4	1Q3	V_{CC}	V_{CC}	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
E	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
H	2Q5	2Q6	V_{CC}	V_{CC}	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
K	$2\overline{OE}$	NC	NC	NC	NC	2CLK

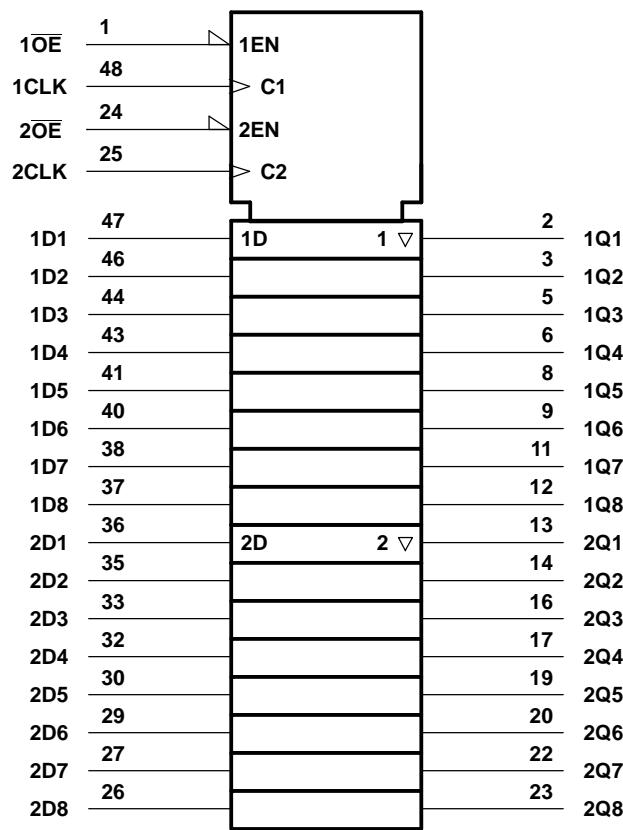
(1) NC - No internal connection

**DGG OR DGV PACKAGE
(TOP VIEW)**



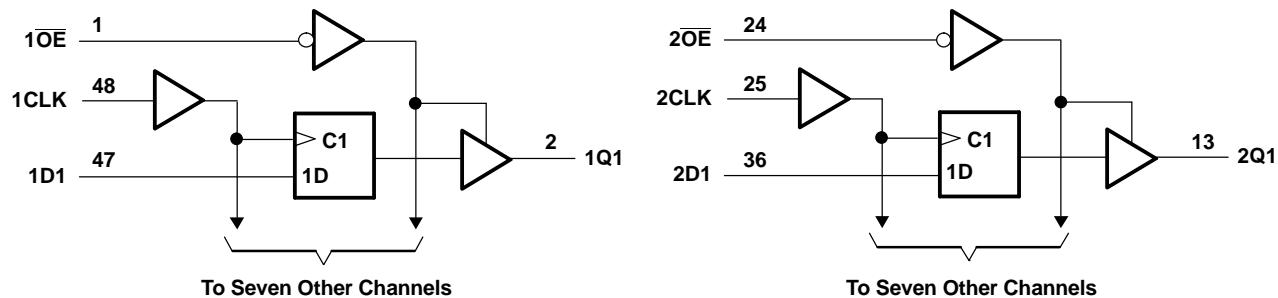
**FUNCTION TABLE
(EACH 8-BIT FLIP FLOP)**

INPUTS			OUTPUT
OE	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q ₀
H	X	X	Z

LOGIC SYMBOL⁽¹⁾

(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range ⁽²⁾	-0.5	4.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	4.6	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current $V_I < 0$		-50	mA
I_{OK}	Output clamp current $V_O < 0$		-50	mA
I_O	Continuous output current		± 50	mA
	Continuous current through each V_{CC} or GND		± 100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package	70	°C/W
		DGV package	58	
		GQL package	42	
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current ratings is observed.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

SN74AVC16374
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP
WITH 3-STATE OUTPUTS

SCES158H—DECEMBER 1998—REVISED MARCH 2005



Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.4	3.6	V
		Data retention only	1.2		
V _{IH}	High-level input voltage	V _{CC} = 1.2 V	V _{CC}		V
		V _{CC} = 1.4 V to 1.6 V	0.65 × V _{CC}		
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 3 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.2 V	GND		V
		V _{CC} = 1.4 V to 1.6 V	0.35 × V _{CC}		
		V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 3 V to 3.6 V	0.8		
V _I	Input voltage		0	3.6	V
V _O	Output voltage	Active state	0	V _{CC}	V
		3-state	0	3.6	
I _{OHS}	Static high-level output current ⁽²⁾	V _{CC} = 1.4 V to 1.6 V	-2		mA
		V _{CC} = 1.65 V to 1.95 V	-4		
		V _{CC} = 2.3 V to 2.7 V	-8		
		V _{CC} = 3 V to 3.6 V	-12		
I _{OLS}	Static low-level output current ⁽²⁾	V _{CC} = 1.4 V to 1.6 V	2		mA
		V _{CC} = 1.65 V to 1.95 V	4		
		V _{CC} = 2.3 V to 2.7 V	8		
		V _{CC} = 3 V to 3.6 V	12		
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 1.4 V to 3.6 V	5	ns/V	
T _A	Operating free-air temperature		-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (2) Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number SCEA009.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OHS} = -100 μ A		1.4 V to 3.6 V	V _{CC} - 0.2			V
	I _{OHS} = -2 mA, V _{IH} = 0.91 V		1.4 V		1.05		
	I _{OHS} = -4 mA, V _{IH} = 1.07 V		1.65 V		1.2		
	I _{OHS} = -8 mA, V _{IH} = 1.7 V		2.3 V		1.75		
	I _{OHS} = -12 mA, V _{IH} = 2 V		3 V		2.3		
V _{OL}	I _{OLS} = 100 μ A		1.4 V to 3.6 V		0.2		V
	I _{OLS} = 2 mA, V _{IL} = 0.49 V		1.4 V		0.4		
	I _{OLS} = 4 mA, V _{IL} = 0.57 V		1.65 V		0.45		
	I _{OLS} = 8 mA, V _{IL} = 0.7 V		2.3 V		0.55		
	I _{OLS} = 12 mA, V _{IL} = 0.8 V		3 V		0.7		
I _I	V _I = V _{CC} or GND		3.6 V		±2.5	μ A	
I _{off}	V _I or V _O = 3.6 V		0		±10	μ A	
I _{OZ}	V _O = V _{CC} or GND		3.6 V		±10	μ A	
I _{CC}	V _I = V _{CC} or GND, I _O = 0		3.6 V		40	μ A	
C _i	Control inputs	V _I = V _{CC} or GND		2.5 V		3	pF
				3.3 V		3	
C _o	Data inputs	V _I = V _{CC} or GND		2.5 V		2.5	
				3.3 V		2.5	
C _o	Outputs	V _O = V _{CC} or GND		2.5 V		6.5	pF
				3.3 V		6.5	

(1) Typical values are measured at V_{CC} = 2.5 V and 3.3 V, T_A = 25°C.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

			V _{CC} = 1.2 V	V _{CC} = 1.5 V \pm 0.1 V	V _{CC} = 1.8 V \pm 0.15 V	V _{CC} = 2.5 V \pm 0.2 V	V _{CC} = 3.3 V \pm 0.3 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency					160	200	200	MHz
t _w	Pulse duration, CLK high or low				3.1	2.5	2.5	2.5	ns
t _{su}	Setup time, data before CLK↑	4.1	2.7		1.9	1.4	1.4	1.4	ns
t _h	Hold time, data after CLK↑	1.7	1.3		1.2	1.1	1.1	1.1	ns

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2 through Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.2 V	V _{CC} = 1.5 V \pm 0.1 V	V _{CC} = 1.8 V \pm 0.15 V	V _{CC} = 2.5 V \pm 0.2 V	V _{CC} = 3.3 V \pm 0.3 V	UNIT				
			TYP	MIN	MAX	MIN	MAX					
f _{max}						160	200	200	MHz			
t _{pd}	CLK	Q	7.3	1.5	8.4	1.2	6.7	0.8	4.1	0.7	3.3	ns
t _{en}	OE	Q	7.4	1.6	8.5	1.6	6.7	0.9	4.3	0.7	3.4	ns
t _{dis}	OE	Q	8.4	2.5	9.4	2.3	7.8	1	4.2	1.5	3.9	ns

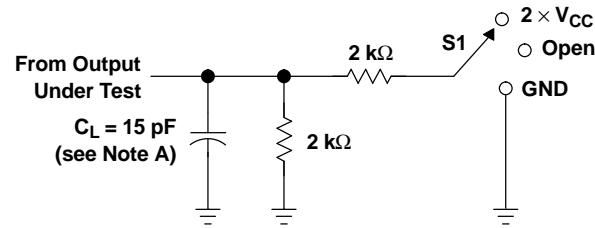
SN74AVC16374**16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP
WITH 3-STATE OUTPUTS**

SCES158H—DECEMBER 1998—REVISED MARCH 2005

Operating Characteristics $T_A = 25^\circ\text{C}$

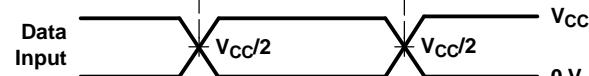
PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	UNIT
		TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	Outputs enabled	$C_L = 0, f = 10 \text{ MHz}$	74	81	89
	Outputs disabled		52	57	63

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 1.2\text{ V AND }1.5\text{ V} \pm 0.1\text{ V}$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

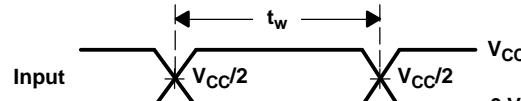
LOAD CIRCUIT



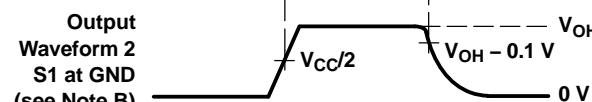
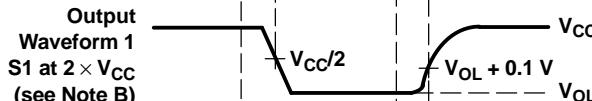
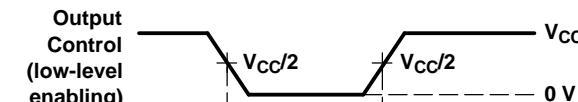
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



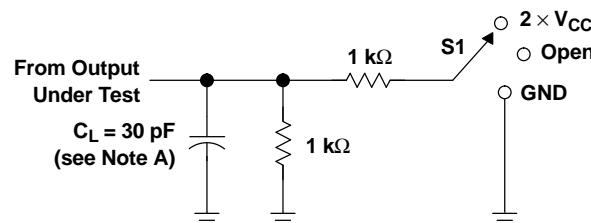
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PZL} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .

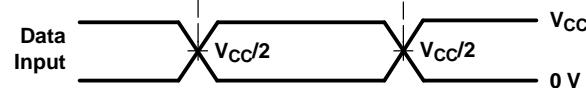
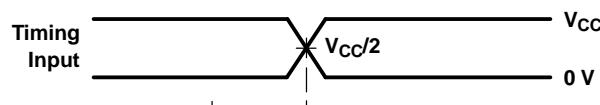
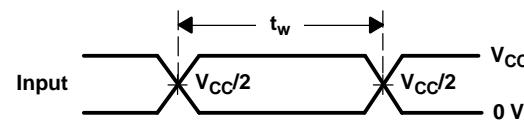
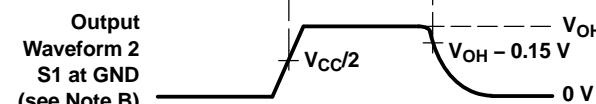
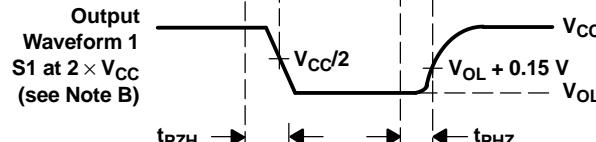
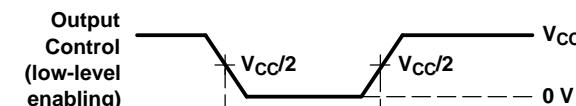
Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

 $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$ 

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

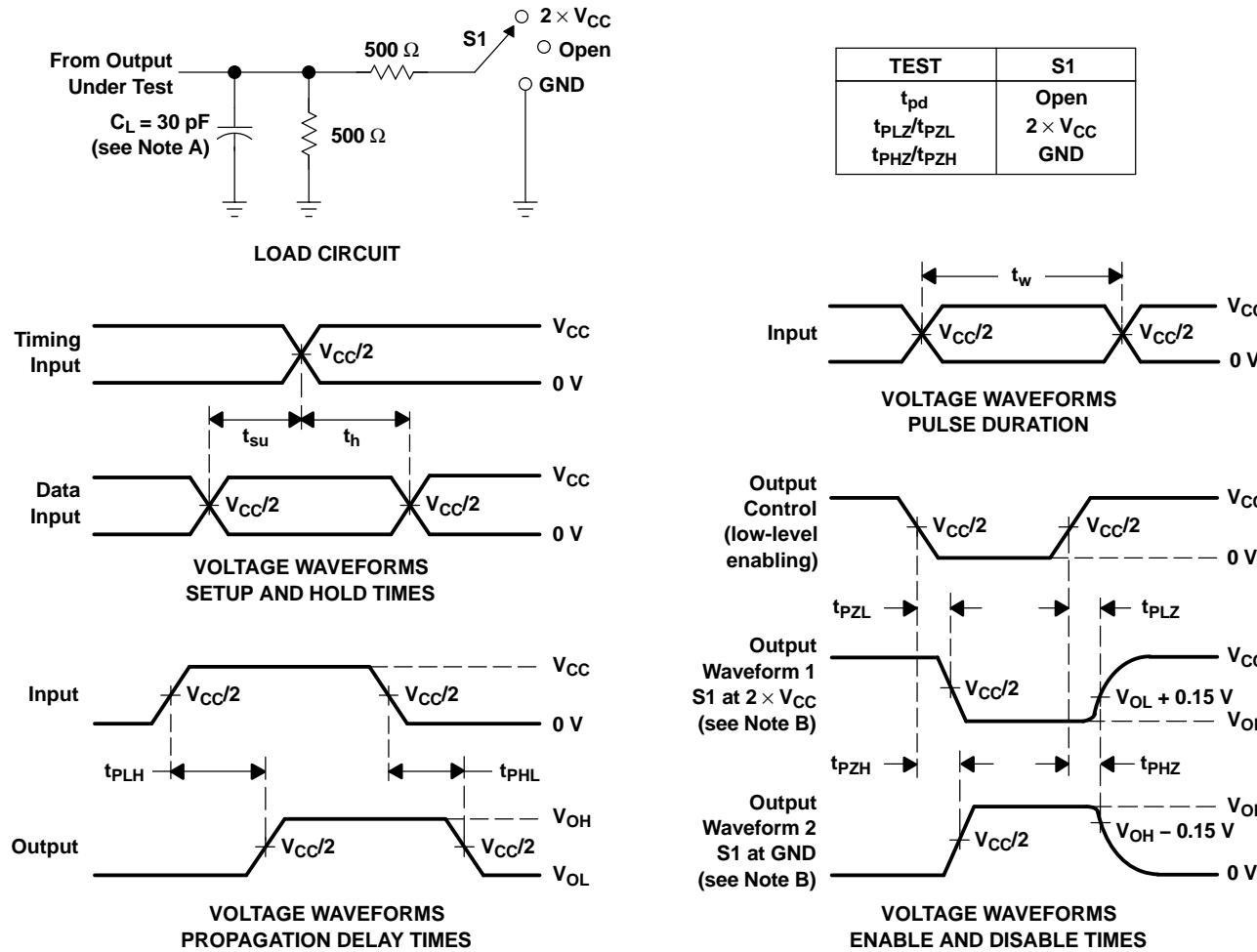
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMESVOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PZL} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

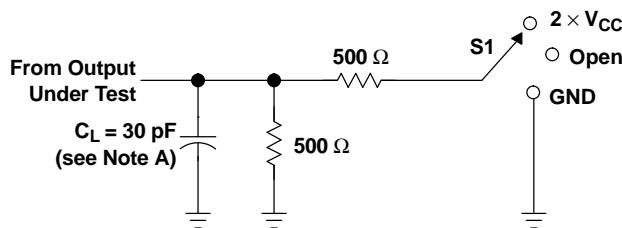
F. t_{PZL} and t_{PZH} are the same as t_{en} .

G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 4. Load Circuit and Voltage Waveforms

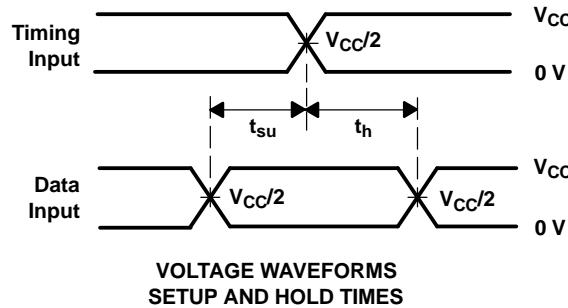
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$

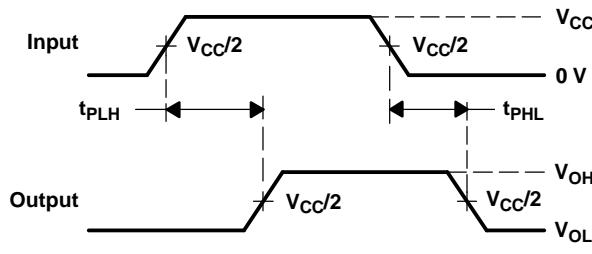


LOAD CIRCUIT

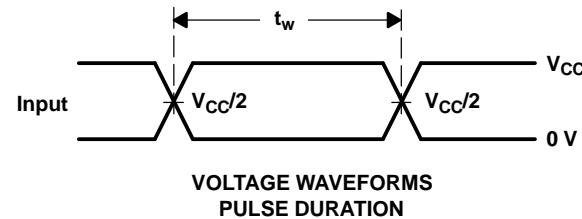
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



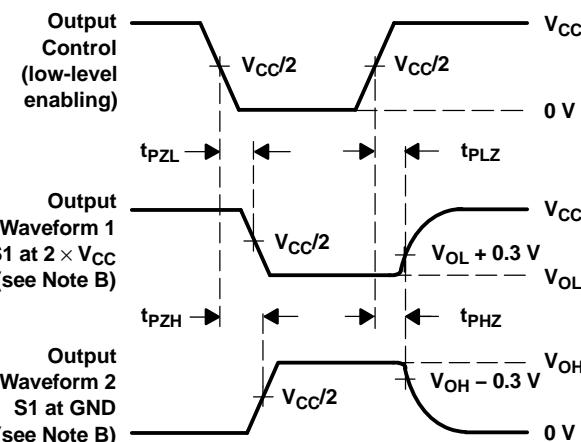
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

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- t_{PZL} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 5. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AVC16374DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC16374
SN74AVC16374DGGR.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC16374
SN74AVC16374DGGRG4	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC16374
SN74AVC16374DGGRG4.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC16374
SN74AVC16374DGVR	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA374
SN74AVC16374DGVR.B	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA374
SN74AVC16374DGVRG4	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA374
SN74AVC16374DGVRG4.B	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA374

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

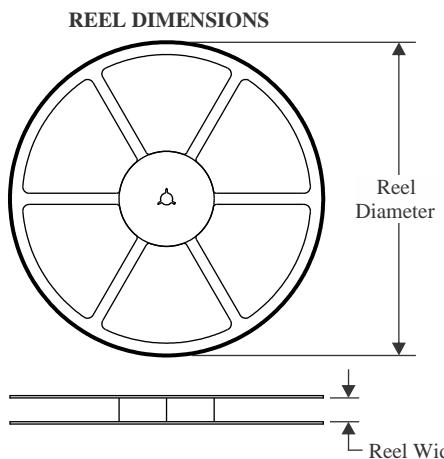
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

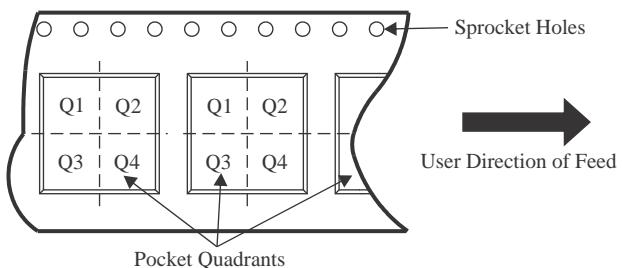
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC16374DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AVC16374DGGRG4	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AVC16374DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AVC16374DGVRG4	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

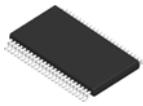
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC16374DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74AVC16374DGGRG4	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74AVC16374DGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74AVC16374DGVRG4	TVSOP	DGV	48	2000	353.0	353.0	32.0

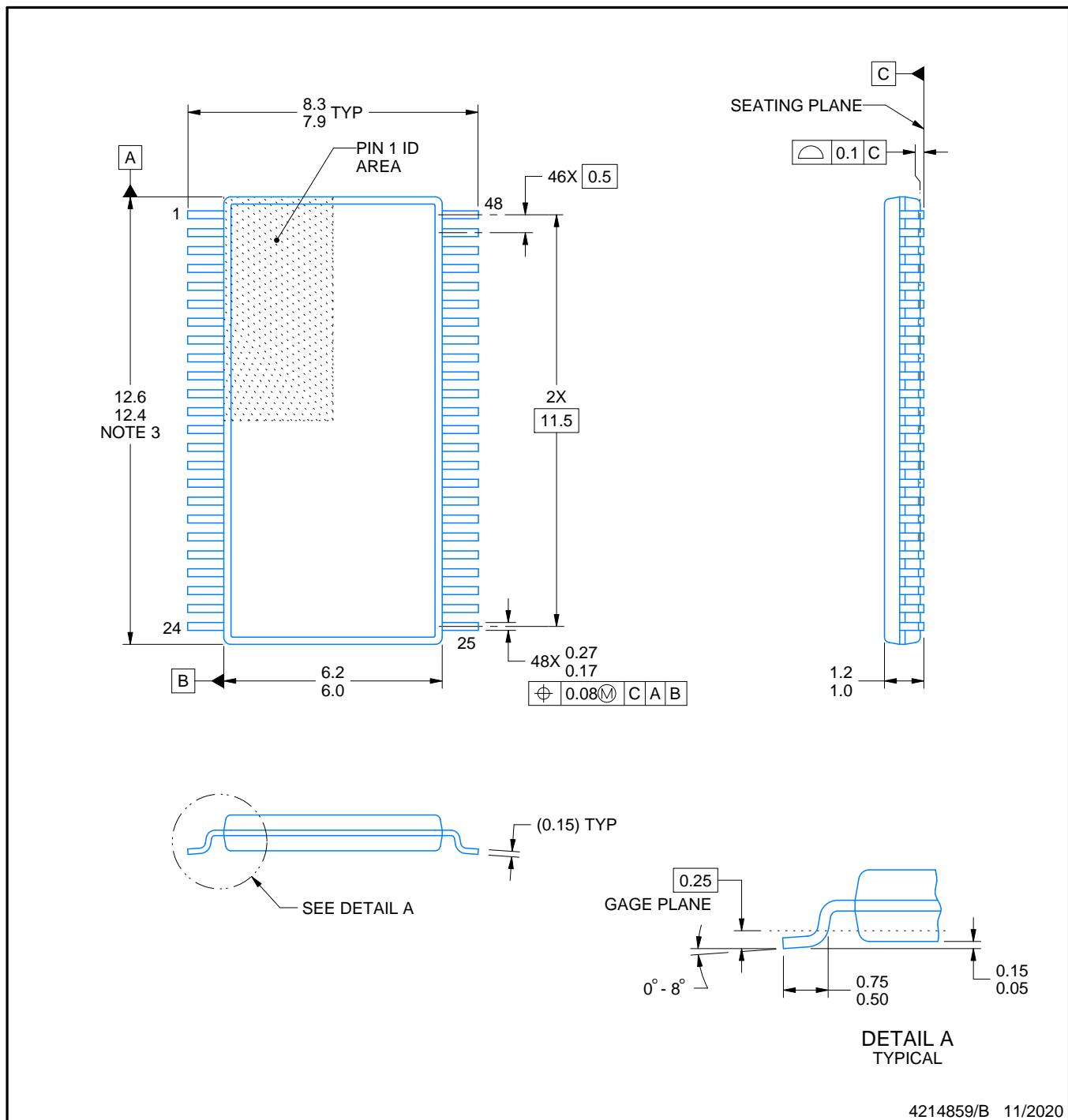
PACKAGE OUTLINE

DGG0048A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

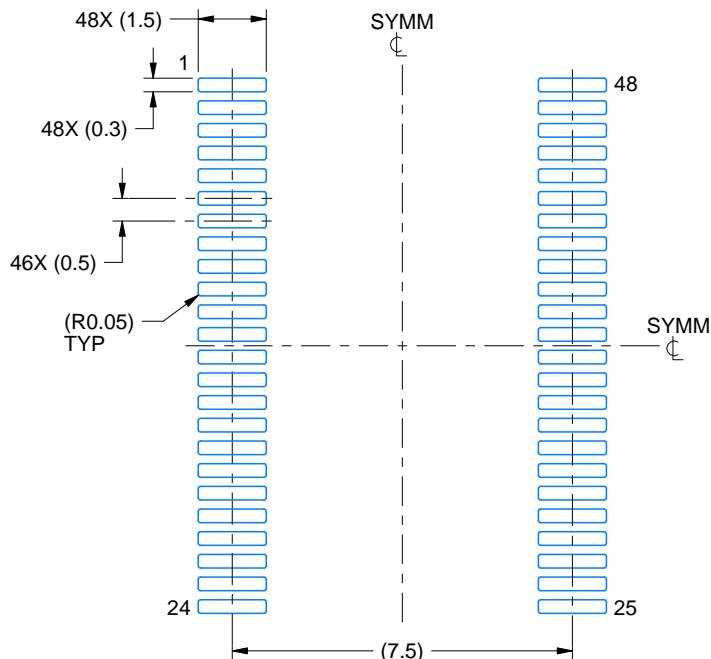
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

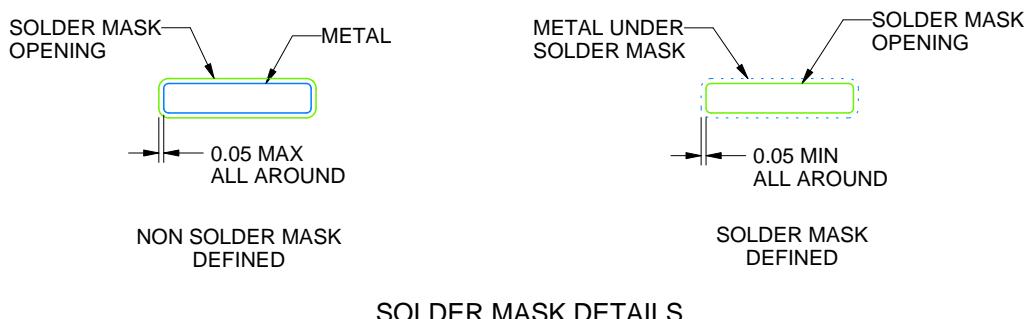
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

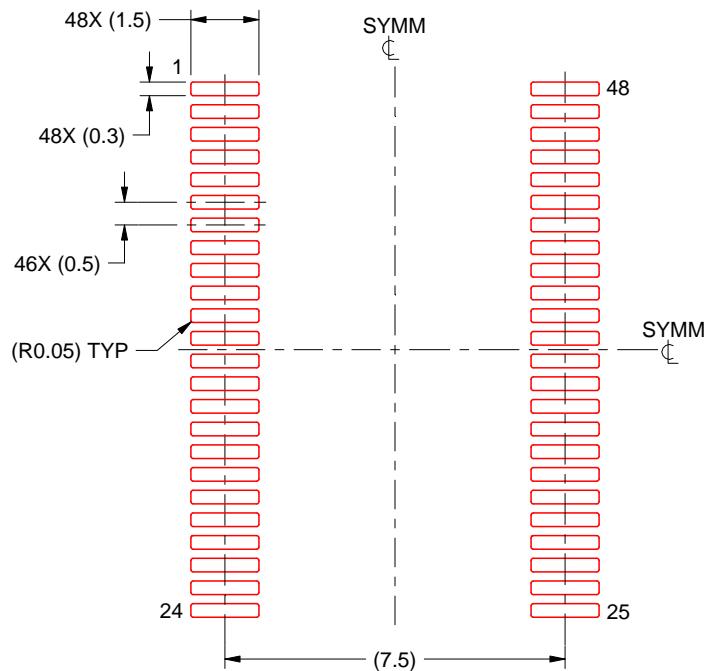
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B 11/2020

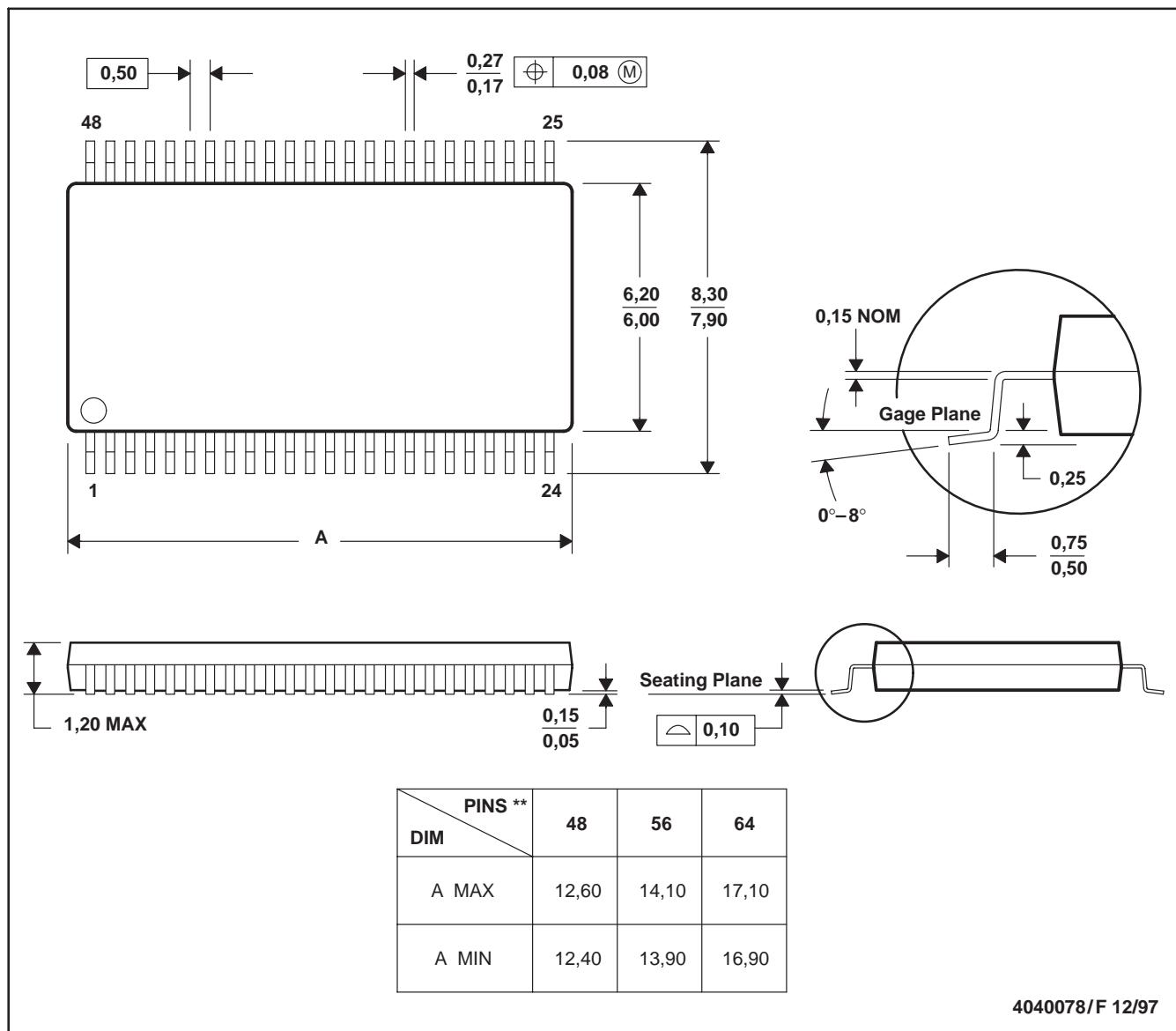
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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